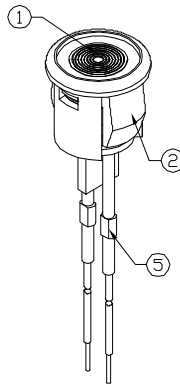
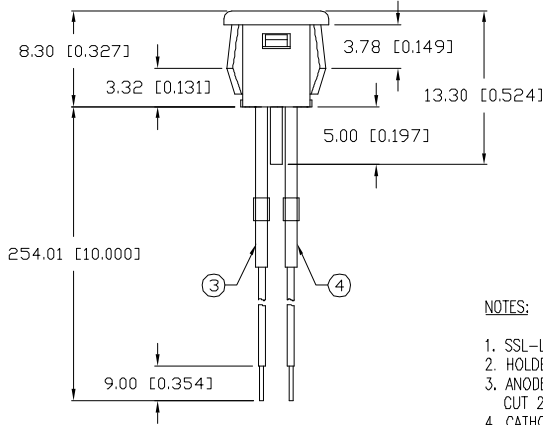
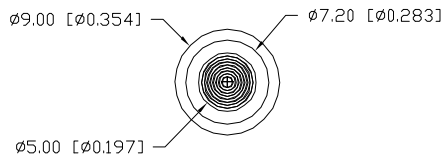


UNCONTROLLED DOCUMENT



NOTES:

1. SSL-LX433ID LED.
2. HOLDER: LXP-SSI-387BSH, LXP-SSI-387BZL.
3. ANODE LEAD: LXP-WST24RDT0C STRANDED, CUT 234mm, STRIP 4mm & 9mm.
4. CATHODE LEAD: LXP-WST24BLT0C STRANDED, CUT 234mm, STRIP 4mm & 9mm.
5. CRIMP LEADS EXTERNAL TO HOUSING. HEAT SHRINK OVER CRIMP-2 PLS.
6. PANEL HOLE CUT OUT: 5/16" DIAMETER.

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION -0.00, MAX= +0.00 -DECIMAL PRECISION

PART NUMBER
SSI-LXH387ID-255

REV.
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	8.2.01

ELECTRO-OPTICAL CHARACTERISTICS T _A =25°C I _f =20mA					
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	V _f	
REVERSE VOLTAGE	5.0			V _r	I _r =100µA
AXIAL INTENSITY		10		mcd	I _f =20mA
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	RED DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

* t<10µS

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REV. A PART NUMBER SSI-LXH387ID-255

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T-5 FRESNEL LENS PANEL INDICATOR,
635nm HIGH INTENSITY RED LED, RED DIFFUSED LENS,
WITH 10" WIRE LEADS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 10.27.97 PAGE: 1 OF 1 SCALE: N/A
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